L Number	Hits	Search Text	DB	Time stamp
1	68153	adhesive near bond\$	USPAT;	2004/07/14
-			US-PGPUB;	16:01
			EPO; JPO;	
			DERWENT;	
]		IBM TDB	
2	33405	induction near heating	USPAT;	2004/07/14
			US-PGPUB;	16:02
			EPO; JPO;	
			DERWENT;	
	100		IBM_TDB	
3	192	susceptor near thickness	USPAT;	2004/07/14
	Ì		US-PGPUB;	16:03
			EPO; JPO; DERWENT;	
			IBM TDB	
4	41659	eddy near current	USPAT;	2004/07/14
7	41039	eddy hear current	US-PGPUB;	16:03
			EPO; JPO;	10.03
			DERWENT;	
			IBM TDB	
5	118170	219/\$.ccls.	USPAT;	2004/07/14
			US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	•
6	679	(adhesive near bond\$) and (induction near	USPAT;	2004/07/14
		heating)	US-PGPUB;	16:03
			EPO; JPO;	
			DERWENT;	
-	3.4		IBM_TDB	2004/07/14
7	14	(susceptor near thickness) and ((adhesive	USPAT;	2004/07/14
		near bond\$) and (induction near heating))	US-PGPUB; EPO; JPO;	16:03
			DERWENT;	
			IBM TDB	
8	14	(eddy near current) and ((susceptor near	USPAT;	2004/07/14
_	11	thickness) and ((adhesive near bond\$) and	US-PGPUB;	16:03
		(induction near heating)))	EPO; JPO;	
		j	DERWENT;	
	.		IBM_TDB	
9	8	219/\$.ccls. and ((eddy near current) and	USPAT;	2004/07/14
		((susceptor near thickness) and	US-PGPUB;	16:03
		((adhesive near bond\$) and (induction	EPO; JPO;	
		near heating))))	DERWENT;	
			IBM_TDB	